

ABSTRACT

BONDING MACHINES FOR BONDING SEMICONDUCTOR ELEMENTS, METHODS OF OPERATING BONDING MACHINES, AND TECHNIQUES FOR IMPROVING UPH ON SUCH BONDING MACHINES

A method of operating a bonding machine is provided. The method includes the steps of: (a) carrying a semiconductor element with a transfer tool; and (b) transferring the semiconductor element from the transfer tool to a bonding tool of the bonding machine without the transfer tool and the bonding tool contacting the semiconductor element at the same time.

Fig. 2